

HyperPAC

Programmable Industrial PC



The HyperPAC Industrial PC programmable control solution delivers top of the line performance with reliable operation for a variety of control and automation tasks. Compared to standard IPCs, the HyperPAC provides a highly compact, fanless solution, with existing expandable IO via PCIe, along with flexibility to expand and configure the system. The HyperPAC is a flexible, scalable solution for numerous applications and project requirements which enables IIoT integration.

Advancements in data accessibility along with reduced data storage costs have resulted in a tremendous demand for improved automation control and data analysis. The future of industry 4.0 smart factory and intelligent manufacturing movements begin with the MKS HyperPAC. MKS' solution will simplify integrating sensors and their corresponding data, structure data from multiple sources, perform real-time analysis of the data, and therefore create actionable information, and visualizations of this information which can be customized for various users.

Product Features

- 5x Ethernet ports
- Front access diagnostics
- Support Xeon® server-grade processor max 35W
- Intel® C236 PCH
- 2 SSD (1x removable, 1x internal)
- DDR4 ECC Memory (Error Correcting Code)
- Easy installation design for expand slot (PCIe x 1)
- Smart fan (optional) with PWM function
- EtherCAT®/DeviceNet™ master capability



Key Benefits

- Ease of fieldbus protocols integration with IIoT solution
- Compact form factor
- Robust IPC
- Flexible configuration

Specifications

System

| | |
|------------------|--|
| CPU | Intel Xeon E3-1268L v5, 2.40 GHz, 35W |
| Storage Device | 2.5" Drive Bay SSD removable 2.5" Drive Bay SSD fixed |
| Chipset | Intel C236 PCH |
| Memory | DDR4 16GB ECC SODIMM x 2, up to 32GB |
| Operating System | Windows® 10 IoT Enterprise LTSB, TenAsys INtime RTOS for Windows |

I/O Interface

| | |
|---------------|--|
| Display | 2x HDMI type A for HDMI v1.4b 1x VGA |
| USB | |
| Front Panel | USB 2.0 x 2 Type A connector |
| Back Panel | USB 3.0 x 4 Type A connector |
| Ethernet | RJ-45 x 5 for GbE (intel I211AT x I219LM x 1) |
| Audio | Audio x 2 (MIC-in, Line-out) |
| Power | 2 x on/off switch (1 on front and 1 on back) 2 pin remote power on/off connector 1x 3-pin DC power input (+, -, GND) |
| Communication | 1x DB-9 ports for RS-232/422/485 |

Expansion Slots

| | |
|--------|----------------------------|
| Slot 1 | Full size mini card (PCIe) |
| Slot 2 | Full size mini card (PCIe) |
| Slot 3 | PCIEx[1] * 1 |

Power Requirement

| | |
|-------------------|--------------------------------|
| Power Input | 12 - 24 VDC |
| Power Consumption | Max 35 W (CPU); 120W (Adapter) |

Mechanical

| | |
|------------------------|-------------------------------------|
| Mounting | Wallmount (horizontal and vertical) |
| Dimensions (W x H x D) | 195mm x 110 mm x 260 mm |
| Net Weight | 9.9 lb (4.9 kg) |

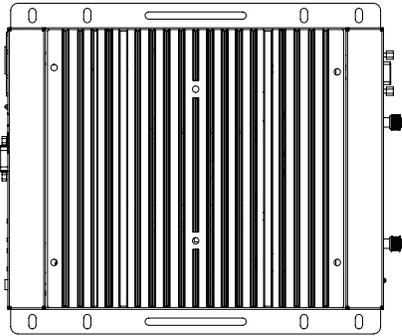
Environmental

| | |
|--------------------------|---|
| Operating Temperature | 0°C ~ 55°C according to IEC60068-2 with 0.5m/s airflow (with smart fan) |
| Storage Temperature | -40°C ~ 80°C |
| Relative Humidity | 5% to 95%, @ 40°C, non-condensing |
| Vibration | Random, 1GRMS, 5~500Hz, anti-vibration design |
| Shock Tolerance/Immunity | 15 G (1/2 sine, 11 ms) |

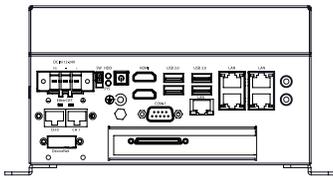
Qualification

| | |
|------------|-----------------|
| Compliance | CE, FCC Class A |
|------------|-----------------|

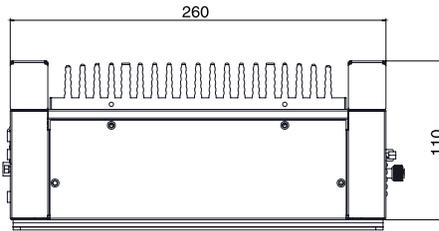
Dimensional Drawing



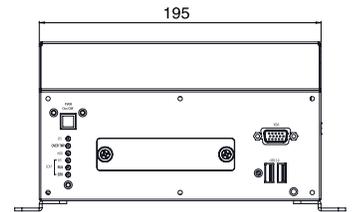
Top View



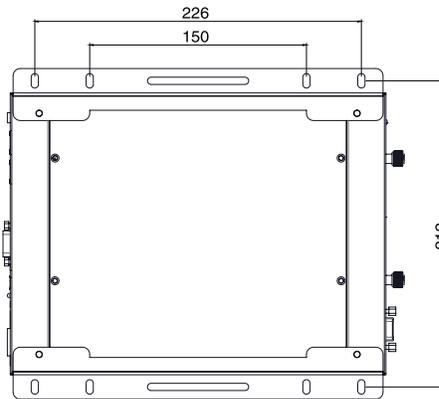
Rear View



Side View



Front View



Bottom View

Note: Unless otherwise specified, dimensions are nominal values in millimeters.

Ordering Information

HyperPAC Programmable Industrial PC

| Part Number | Description |
|-------------|--|
| AS08640G-01 | Industrial PC, Xeon CPU, 32GB ECC DRAM, PWM fan option |

Please contact your local MKS office for price and availability information.



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